# **Technical Data Sheet**

# **Chip LED with Right Angle Lens**

### Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS complaint version

### Descriptions

- The 12-21 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

### Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

## **Device Selection Guide**

DAN	Chip		Resin Color	
Part No.	Material	<b>Emitted</b> Color		
12-21/BHC-AP1Q2M/2C	InGaN	Blue	Water Clear	

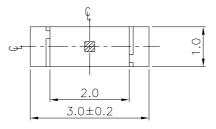


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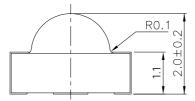


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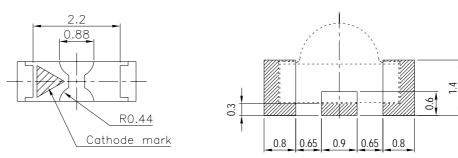
## **Package Outline Dimensions**







For reflow soldering (propose)



**Note:** The tolerances unless mentioned is  $\pm 0.1$  mm ,Unit = mm



# 12-21/BHC-AP1Q2M/2C

## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	Vr	5	V
Forward Current	IF	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	Ifp	100	mA
Power Dissipation	Pd	95	mW
Electrostatic Discharge(HBM)	ESD	150	V
Operating Temperature	Topr	$-40 \sim +85$	°C
Storage Temperature	Tstg	-40 ~ +90	°C
Soldering Temperature	Tsol	Reflow Soldering : $260 \degree C$ for 10 sec. Hand Soldering : $350 \degree C$ for 3 sec.	

## Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
1 drameter	Symoor	141111.	Typ.	Iviax.	Om	Condition
Luminous Intensity	Iv	45.0		112.0	mcd	
Viewing Angle	2 <del>0</del> 1/2		120		deg	
Peak Wavelength	λp		468		nm	
Dominant Wavelength	λd	464.5		476.5	nm	IF=20mA
Spectrum Radiation Bandwidth	$ riangle \lambda$		35		nm	
Forward Voltage	VF	2.75		3.95	V	
Reverse Current	Ir			50	$\mu$ A	V <sub>R</sub> =5V

### Notes:

1.Tolerance of Luminous Intensity ±11%

### 2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage: ±0.1V



# 12-21/BHC-AP1Q2M/2C

## Bin Range Of Dom. Wavelength

Group	Bin	Min	Max	Unit	Condition	
А	A9	464.5	467.5			
	A10	467.5	470.5	nm	IF=20mA	
	A11	470.5	473.5			
	A12	473.5	476.5			

### **Bin Range Of Luminous Intensity**

0	U			
Bin	Min	Max	Unit	Condition
P1	45.0	57.0	mcd	IF=20mA
P2	57.0	72.0		
Q1	72.0	90.0		
Q2	90.0	112.0		

## **Bin Range Of Forward Voltage**

Group	Bin	Min	Max	Unit	Condition	
М	5	2.75	3.05			
	6	3.05	3.35	v	I <sub>F</sub> =20mA	
	7	3.35	3.65			
	8	3.65	3.95			

Notes:

**1.Tolerance of Luminous Intensity ±11%** 

- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage: ±0.1V



# 12-21/BHC-AP1Q2M/2C

Ta=25°C

4.2

+

10

4.5

Ta=25°C

Ta=25°C

30°

40°

50°

60°

70°

80°

90°

#### Forward Current vs. Spectrum Distribution Forward Voltage Ta=25°C 50 100 Relative luminous intensity(%) Forward Current I<sub>F</sub> (mA) 40 75 30 50 25 20 25 10 0 0 - 2.6 400 450 500 550 600 3.0 3.4 3.8 Wavelength $\lambda(nm)$ Forward Voltage V<sub>F</sub> (V) Luminous Intensity vs Luminous Intensity vs. Forward Current Ambient Temperature 1000 Relative luminous intensity (%) Relative luminous intensity (%) f=1KHz Duty=1/10 100 10 1 -60 -40 -20 0 20 40 60 80 100 10 10<sup>1</sup> Ambient Temperature T<sub>a</sub>(°C) Forward Current I<sub>F</sub> (mA) Forward Current Derating Curve **Radiation Diagram** 50 Forward Current I<sub>F</sub> (mA) 40 30 1.0 25 0.9 20 0, 8 10 0.7 0 \_ Ambient Temperature $T_a$ (°C) 100 0.5 0.3 0.1 0. 2

### **Typical Electro-Optical Characteristics Curves**

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0.6

0, 4



# 12-21/BHC-AP1Q2M/2C

### Label explanation

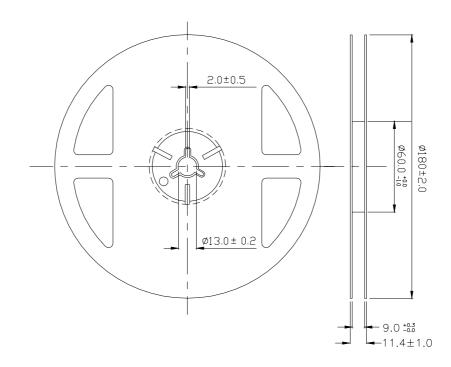
**CAT: Luminous Intensity Rank** 

HUE: Dom. Wavelength Rank

**REF: Forward Voltage Rank** 



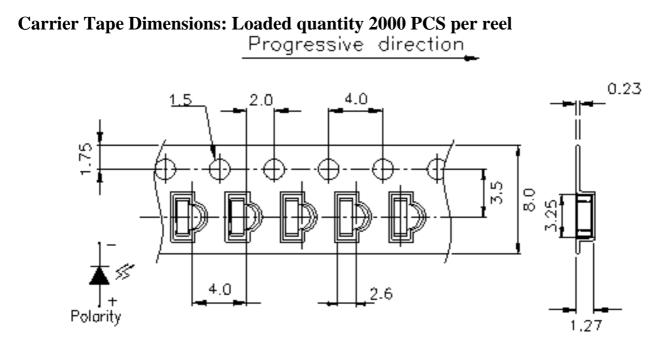
## **Reel Dimensions**



**Note:** The tolerances unless mentioned is  $\pm 0.1$  mm ,Unit = mm

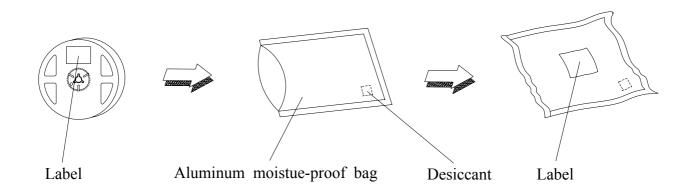


# 12-21/BHC-AP1Q2M/2C



**Note:** The tolerances unless mentioned is  $\pm 0.1$  mm ,Unit = mm

## **Moisture Resistant Packaging**





# 12-21/BHC-AP1Q2M/2C

## **Reliability Test Items And Conditions**

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85℃/ 85%RH	1000 Hrs.	22 PCS.	0/1



# 12-21/BHC-AP1Q2M/2C

## **Precautions For Use**

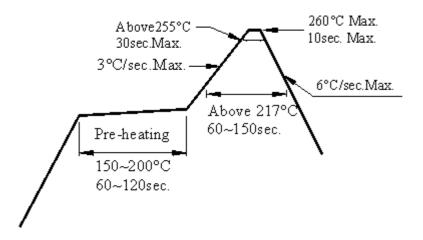
1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change ( Burn out will happen ).

- 2. Storage
  - 2.1 Do not open moisture proof bag before the products are ready to use.
  - 2.2 Before opening the package: The LEDs should be kept at  $30^\circ$ C or less and 90%RH or less.
  - 2.3 After opening the package: The LED's floor life is 1 year under  $30^{\circ}$ C or less and 60% RH or less.

If unused LEDs remain, it should be stored in moisture proof packages.

- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
  Baking treatment : 60±5℃ for 24 hours.
- 3. Soldering Condition
  - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.



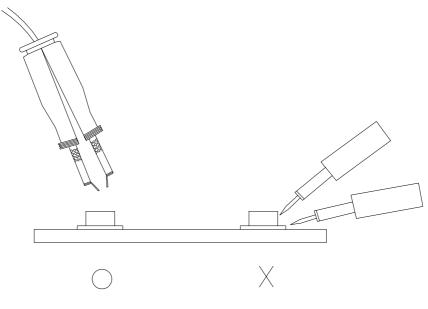
# 12-21/BHC-AP1Q2M/2C

### 4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than  $350^{\circ}$ C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

### 5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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Rev. 1 Page: 10 of 10 Prepared by: Xu juan

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